

## NEXTECK Back Grinding Tape

### Features

- Provides strong adhesion to prevent chip scattering and slurry penetration during grinding.
- Reduces the risk of backside chipping during wafer grinding.
- Minimizes kerf shift to maintain chip alignment and precision.
- Prevents wafer warpage after grinding for improved flatness and yield.

### Selected Specifications

P/N	Base Film	Color	Total Thickness (μm)	Adhesive Thickness (um)	Adhesive Strength (N/20mm)	Probe Tack (N/20mm)	Features
NDT-ATS122	EVA	Light Blue	140	20	1.3	1.19	Standard Types for middle-bumped wafers
NDT-ATS124			160	40	1.41	1.29	
NDT- P Series	PET	Transparent	85	35	18.04	13.97	For detaping back grinding tape

### Recommended Applications

- For middle-bumped wafers & detaping back grinding tape

